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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of: **Hiroshi ITO et al.**

Group Art Unit: 1714

Serial No.: **09/868,657**

Examiner: **J. Robertson**

Filed: **November 7, 2001**

P.T.O. Confirmation No.: 8618

For: **CURABLE RESIN COMPOSITION**

AMENDMENT UNDER 37 C.F.R. §1.111

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

June 30, 2003

Sir:

In response to the Office Action dated March 28, 2003, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Please amend the paragraph beginning on page 5, line 12 as follows:

The curable resin composition comprising a reactive silicon group-containing polyether oligomer with a terminal introduction rate of the reactive silicon group of not less than 85 % not only insures good physical properties required of a sealant (tensile strength at break, elongation at break, cure speed, etc.) but also displays an outstanding adhesive strength. When said introduction rate is less than 85%, the effects of the invention (a high adhesive strength in particular) cannot be obtained. Heretofore, the relationship of the introduction rate of the reactive silicon group to various physical properties, particularly adhesive strength, has not been known. This has just been elucidated by the present inventors for the first time. The present invention is based on this finding.